Instructors

Bruce Archambeault, Ph.D., Senior EMC Engineer, IBM, Research Triangle Park, NC. Industry experience in government/TEMPEST and commercial EMC design, testing and simulation. Expertise includes using various computational techniques to solve real-world EMC problems. Lead author of the book titled “EMI/EMC Computational Modeling Handbook”.

Diganta Das, Ph.D., Faculty at the University of Maryland, College Park. Expertise includes environmental and operational ratings of electronic parts, uprating, part obsolescence prediction and management, technology trends in electronic parts and their effects on parts selection and management, reliability assessment of parts and boards under different environmental conditions.

Abhijit Dasgupta, Ph.D., Faculty at the University of Maryland, College Park. Expertise includes physics of failure analysis, reliability assessment and accelerated qualification of electronic components, assemblies and interconnects; mechanics of material behavior - including thermo-mechanical material constitutive modeling, stress analysis, and damage mechanics of heterogeneous materials and assemblies, and ‘smart’ composites and nanostructures materials. He has published over 220 papers, book chapters and articles, and presented over 50 workshops nationally and internationally on these topics. He has served on the editorial boards of three international journals and received six awards for contributions in research and education.

Craig Hillman, Ph.D., Faculty at the University of Maryland, College Park. Expertise includes process assessment of contract assemblers and contract board manufacturers, virtual qualification techniques for electronic products, design for reliability, and electronic systems failure mechanisms.

Chung-Shing Lee, D.Sc., Assistant Professor of Technology Management, and the Director of Electronic Commerce Resource Center (eplu.org) at the Pacific Lutheran University in Tacoma, Washington. Expertise includes technology and innovation management, supply chain management, electronic commerce business models and strategies, Asian electronics industry analysis, and information management. Industry experience: eight plus years of business consulting experience at Washington, D.C. in the areas of business strategy, economics regulation, and public policy; conduct professional seminars and workshops in electronic commerce and supply chain management for corporate senior and technical managers.

Patrick McCluskey, Ph.D., Faculty at the University of Maryland, College Park. Expertise includes computer aided risk assessment of microelectronics, electronic packaging design for high temperature and high power applications, and the insertion of commercial components into high reliability applications. Author of High Temperature Electronics, CRC Press, Inc., New York, NY, 1997

Michael Osterman, Ph.D., Faculty at the University of Maryland, College Park. Expertise includes virtual qualification techniques for electronic products, failure analysis for electronic systems, and information systems for electronics design.

Michael Pecht, Ph.D., Chair Professor, University of Maryland; College Park; Director of the CALCE Electronic Products and Systems Center; Professional Engineer, IEEE Fellow, ASME Fellow, Westinghouse Fellow, author of 11 books on electronic products and systems, chief editor for Microelectronics Reliability, and former editor of IEEE Transactions on Reliability. Expertise includes competitive electronic product development, reliability methods and tools, product characterization and qualification, supply chain creation and management, risk assessment and mitigation. Consultant for various companies by providing expertise in strategic planning, root cause analysis, design, test and risk assessment of electronics products and systems.

Omar M. Ramahi, Ph.D., Faculty at the University of Maryland, College Park. Industry experience: member of the alpha server product development group at Digital Equipment Corporation (presently Compaq Computer Corporation). Expertise includes computational techniques for electromagnetic radiation problems in the fields of antennas, high-speed devices and circuits and EMI/EMC.

Keith L. Rogers, M.S., Faculty at the University of Maryland, College Park. Mr. Rogers specializes in the area of electronic packaging and works in the materials characterization laboratory of CALCE. His expertise lies in the operation of equipment used in electronic failure analyses and is an instructor of most of the machines. He has authored and co-authored many articles for various trade magazines and technical journals including Advanced Materials & Processes, Circuit World, Printed Circuit Fabrication, IEEE Transactions on Components, Packaging, and Manufacturing Technology, and Proceedings of Advanced Technology, Acquisition, Qualification, and Reliability.

Peter A. Sandborn, Ph.D., Faculty at the University of Maryland, College Park. Expertise includes electronic packaging tradeoff analysis, multichip module design, design to cost, and design for environment; parts selection and management, and detailed cost modeling of electronic packaging. Industry experience: senior member of technical staff at MCC, a founder and the chief technical officer of Savantage, Inc. and a technical contributor at Nu Thena Systems, Inc.